

LULEÅ UNIVERSITY OF TECHNOLOGY

DEPT. OF COMPUTER SCIENCE, ELECTRICAL AND  
SPACE ENGINEERING

X7006E – MASTER THESIS ENGINEERING PHYSICS AND  
ELECTRICAL ENGINEERING

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***Project Evaluation of high peak  
power circuit board simulation  
versus physical tests (subject to  
change)***

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**Abstract**

Summary of entire report

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## 1 Acronyms

1. **PCB** Printed Circuit Board 3, *Glossary*: PCB

## 2 Glossary

2. **PCB** A Printed Circuit Board (PCB) is the common acronym when referring to populated circuit boards. 3

## **3 Introduction**

Introduces the problem

### **3.1 Goals**

What is the goals of this examination job?

#### **3.1.1 Reason**

Why I chose this project?

#### **3.1.2 Usecase**

What can this be used for and what motivates the support from Grepit AB?

### **3.2 Hypothesis**

Whats my hypothesis, what am I expecting?

## **4 System**

Section that describes the tested system

### **4.1 Schematic design**

Schematic of system

### **4.2 Component choices**

Motivates component choices

### **4.3 PCB design**

Describes the Printed Circuit Board (PCB) design that will be tested and simulated. Motivates design choices.

## **5 Method**

Chapter that will describe testing methods and testing setup

### **5.1 Physical measurements**

Will describe the measurement method for the system hardware

#### **5.1.1 setup**

Describes hardware measurement setup

#### **5.1.2 tests**

Describes the measurement method and what they test

### **5.2 Simulations**

Will describe the testing method for the simulations

#### **5.2.1 setup**

Describes simulation setup

#### **5.2.2 tests**

describes the tests and what they mean

## **6 Results**

This sections assembles results gathered from the tests in section 5.

### **6.1 Measurements**

Will summarize measured results

### **6.2 Simulation**

Will summarize simulated results

### **6.3 Comparison**

Will be a short summary of the similarities and differences between simulated results and measured results



## 7 Discussion

Discusses the results from subsection 6.3. What do the similarities and differences mean? Why are they there?

Can this be used in the industry? Is this an useful product for customers? Compare against Hypothesis.

## References

- [1] <https://www.autodesk.com/products/fusion-360/overview>

# Appendices

## A Large Figures

insert pictures

## **B   Lists**

insert lists

LAST WORDS

